

## SMA Plastic-Encapsulate Diodes

### Schottky Rectifier Diode

#### Features:

- $I_{F(AV)}$  5A
- $V_{RRM}$  40V
- High surge current capability
- Polarity: Color band denotes cathode
- Low peak forward voltage

#### Applications:

- Rectifier

#### SMA



#### Marking

- SS54L

#### Chip

- Planar technoloh 70MIL

#### Limiting Values(Absolute Maximum Rating)

Item	Symbol	Unit	Test Conditions	SK54L
Repetitive Peak Reverse Voltage	$V_{RRM}$	V		40
Maximum RMS Voltage	$V_{RMS}$	V		28
Average Forward Current	$I_{F(AV)}$	A	60Hz Half-sine wave , Resistance load	5.0
Surge(Non-repetitive)Forward Current	$I_{FSM}$	A	60Hz Half-sine wave , 1 cycle , $T_a=25^{\circ}C$	120
Junction Temperature	$T_J$	$^{\circ}C$		-55 ~ +150
Storage Temperature	$T_{STG}$	$^{\circ}C$		-55 ~ +150

#### Electrical Characteristics (T=25 $^{\circ}C$ Unless otherwise specified)

Item	Symbol	Unit	Test Condition		SK54L
Peak Forward Voltage	$V_F$	V	$I_F=5.0A$	$T_a=25^{\circ}C$	0.43
Peak Reverse Current	$I_{RRM1}$	mA	$V_{RM}=V_{RRM}$	$T_a=25^{\circ}C$	0.2
	$I_{RRM2}$			$T_a=100^{\circ}C$	20
Thermal Resistance(Typical)	$R_{\theta J-A}$	$^{\circ}C/W$	Between junction and ambient		75
	$R_{\theta J-L}$		Between junction and lead		27
Juction Capacitance (Typical)	$C_j$	pF	Measured at 1MHZ and Applied Reverse Voltage of 4.0 V.D.C		210

#### Notes:

Thermal resistance from junction to ambient and from junction to lead mounted on FR4 PCB double sided copper mini pad

### Typical Characteristics

FIG. 1: FORWARD CURRENT DERATING CURVE

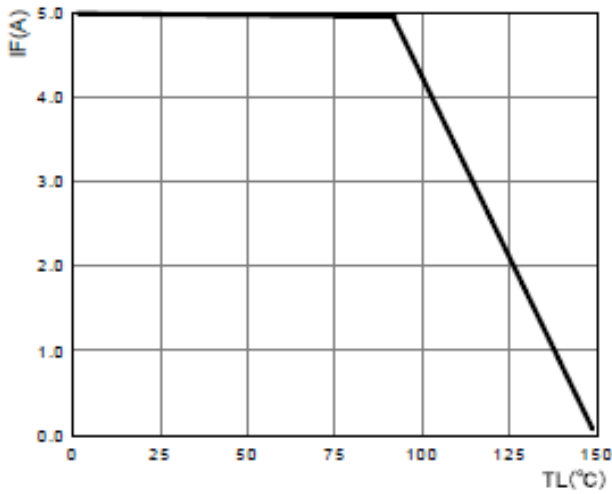


FIG. 2: MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

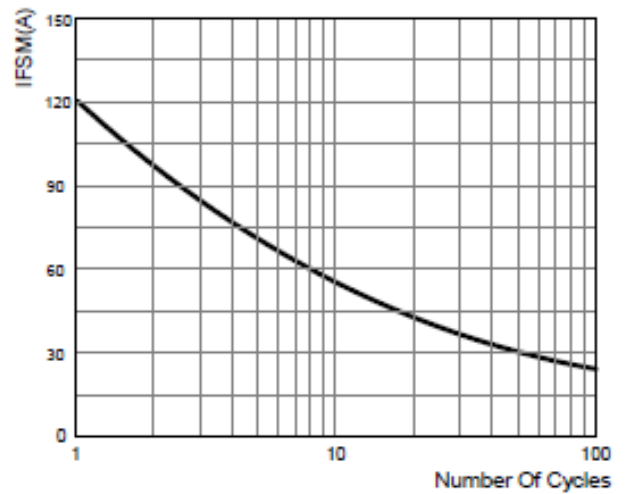


FIG. 3: TYPICAL FORWARD CHARACTERISTICS

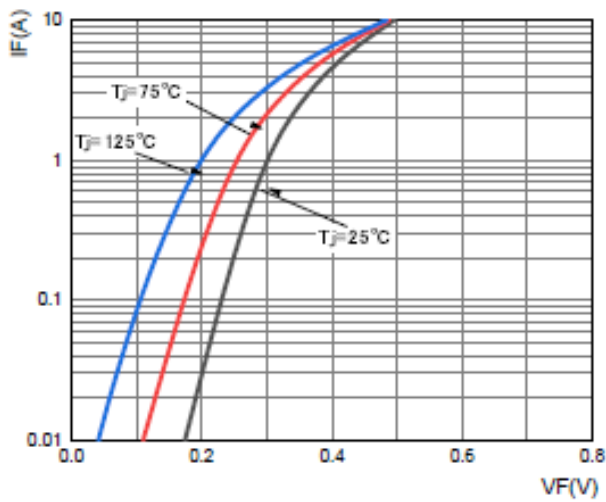
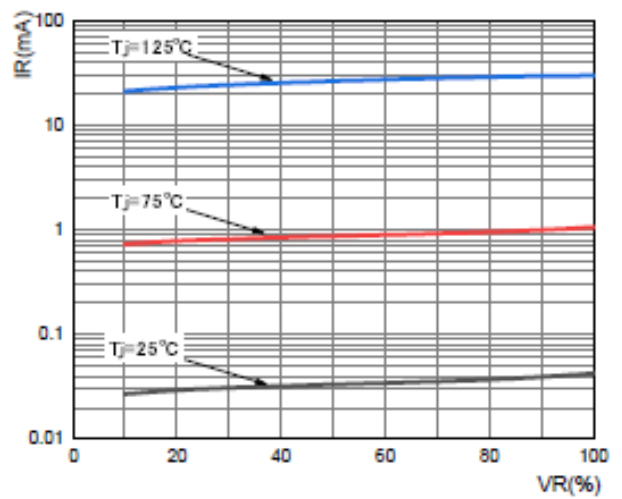
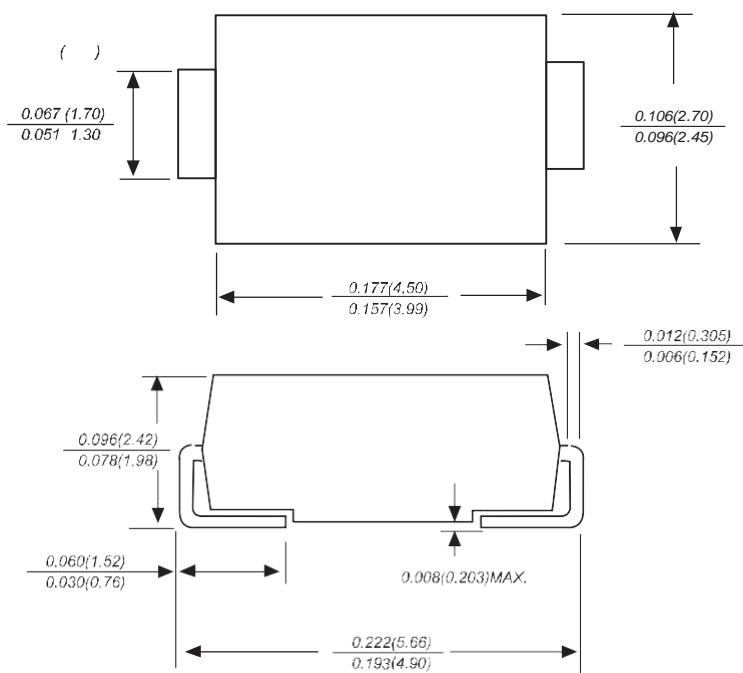


FIG. 4: TYPICAL REVERSE CHARACTERISTICS

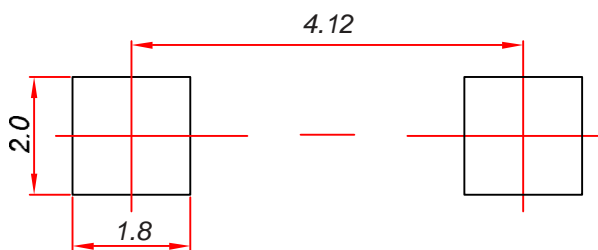


### SMA Package Outline Dimensions



Dimensions in inches and (millimeters)

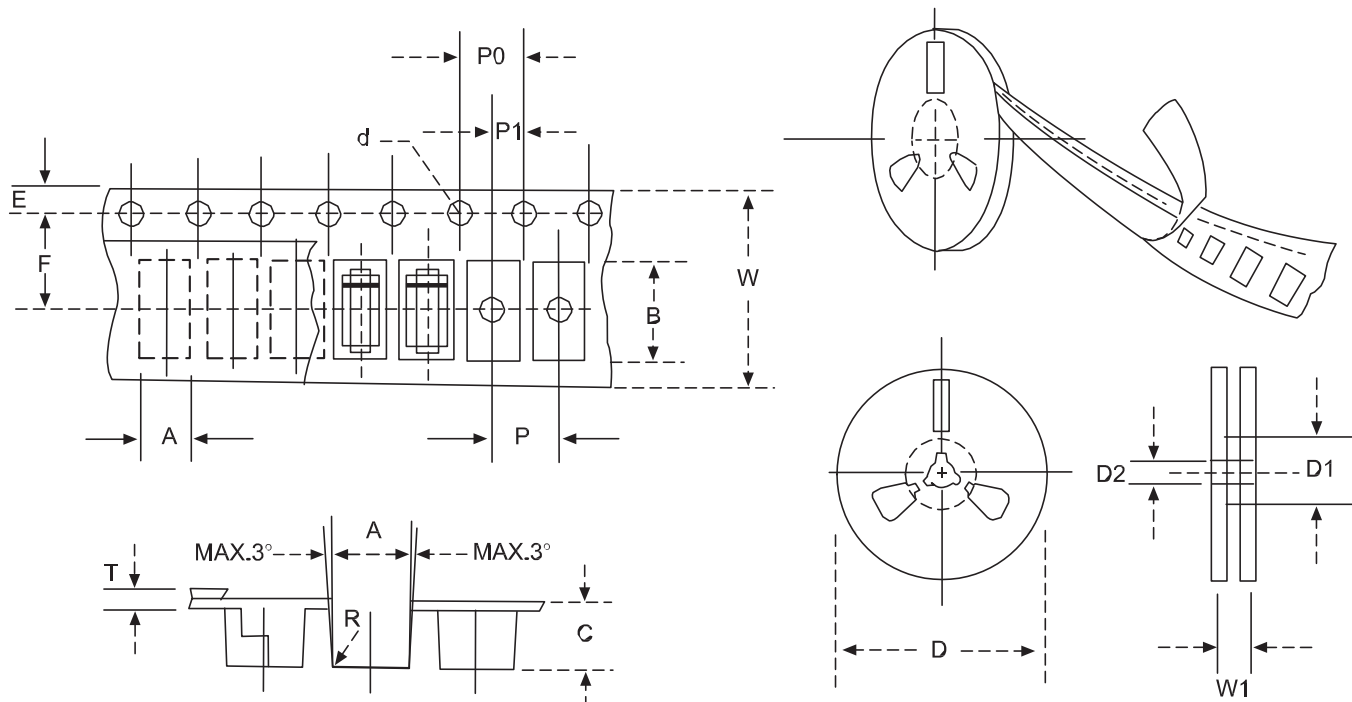
### SMA Suggested Pad Layout



**Note:**

1. Controlling dimension: in millimeters.
2. General tolerance:  $\pm 0.05$ mm.
3. The pad layout is for reference purposes only.

**Reel Taping Specifications For Surface Mount Devices- SMA**



**FIG: CONFIGURATION OF SURFACE MOUNTED DEVICES TAPING**

ITEM	SYMBOL	SMA mm(inch)
Carrier width	A	2.79±0.1(0.110±0.004)
Carrier length	B	5.33±0.1(0.210±0.004)
Carrier depth	C	2.36±0.1(0.093±0.004)
Sprocket hole	d	1.55±0.05(0.061±0.002)
Reel outside diameter	D	279±2.0 (11± 0.079)
Reel inner diameter	D1	75±1.0 ( 2.95 ±0.039)
Feed hole diameter	D2	13±0.5(0.512±0.020)
Sprocket hole position	E	1.75±0.1(0.069±0.004)
Punch hole position	F	5.5±0.05(0.217±0.002)
Punch hole pitch	P	4.0±0.1(0.157±0.004)
Sprocket hole pitch	P0	4.0±0.1(0.157±0.004)
Embossment center	P1	2.0±0.1(0.079±0.004)
Total tape thickness	T	0.28±0.02(0.011±0.0008)
Tape width	W	12.0±0.2(0.472±0.008)
Reel width	W1	16.8±2.0(0.661±0.079)

NOTE: Devices are packed in accordance with EIA standard RS-481-A and specification given above.